

Embedded Tutorial:

"BEYOND CMOS - BENCHMARKING FOR FUTURE TECHNOLOGIES"

Moderators:

Prof Clivia M Sotomayor Torres,
Catalan Institute of Nanotechnology, Barcelona, Spain

Prof Wolfgang Rosenstiel,
edacentrum and University of Tuebingen, Germany



NANO-TEC has received funding from the European Community's Seventh Framework Programme (FP7/2007-2013) under grant agreement n° 257964

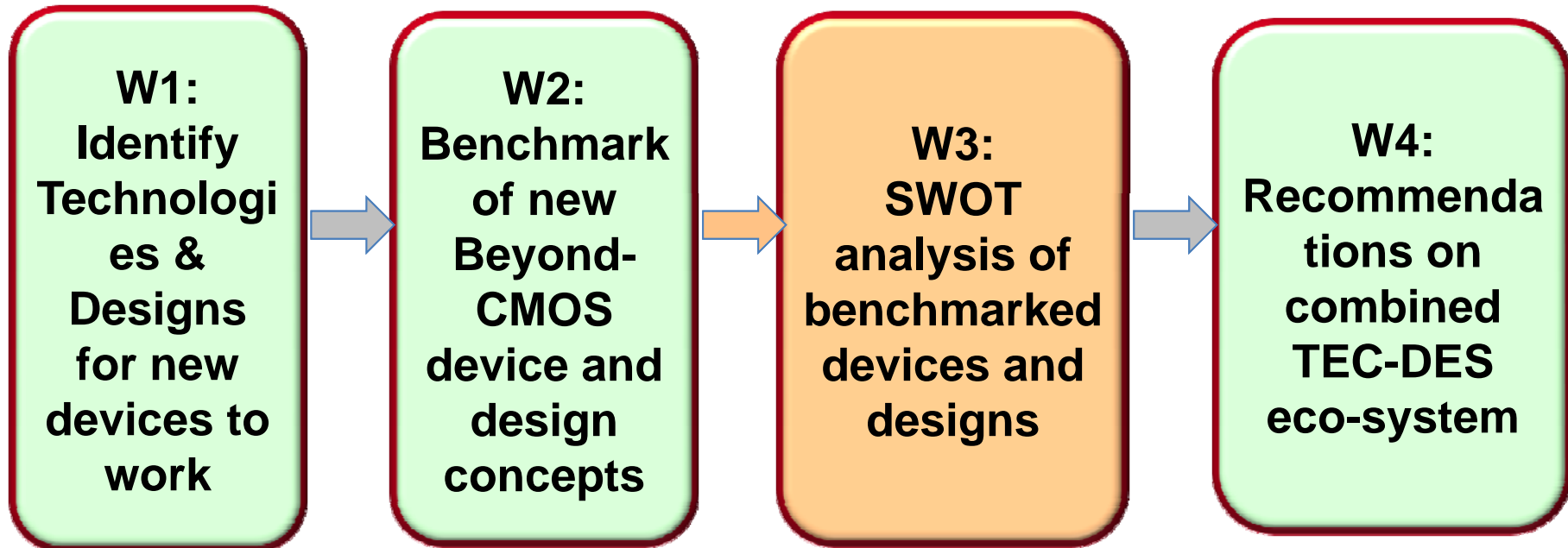
About NANO-TEC

AIMS

- ❑ To identify the next generation of (emerging) device concepts and technologies for ICT.
- ❑ To build a joint technology-design community to coordinate research efforts in nanoelectronics.



NANO-TEC timeline



January 2010
Granada

October 2011
Athens

30-31 May 2012
Lausanne

Autumn 2012

Presentations

- **Emerging Technologies: More Moore and More than Moore**
 - Dr Mart Graef, Delft University of Technology, The Netherlands
- **Technology and Design challenges in future low power memory devices and circuits**
 - Dr Paolo Fantini, Micron Semiconductors, Italy
- **Bridging Technology and Design for Beyond CMOS**
 - Prof Paolo Lugli (tentative), Technical University of Munich, Germany
- **Bridging Technology and design in More than Moore**
 - Dr Wladek Grabinski, EPFL, Switzerland
- **Benchmarking for Beyond CMOS technologies**
 - Prof Jouni Ahopelto VTT, Finland

Emerging Technologies: *More Moore and More than Moore*

**Dr Mart Graef,
Delft University of Technology,
The Netherlands,
m.w.m.graef@tudelft.nl**



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Overview

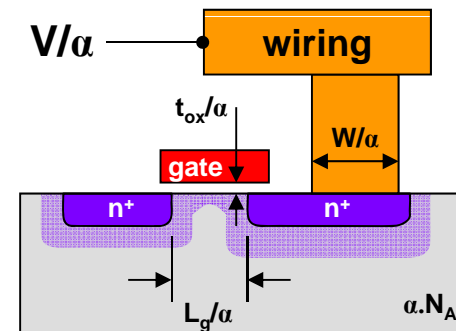
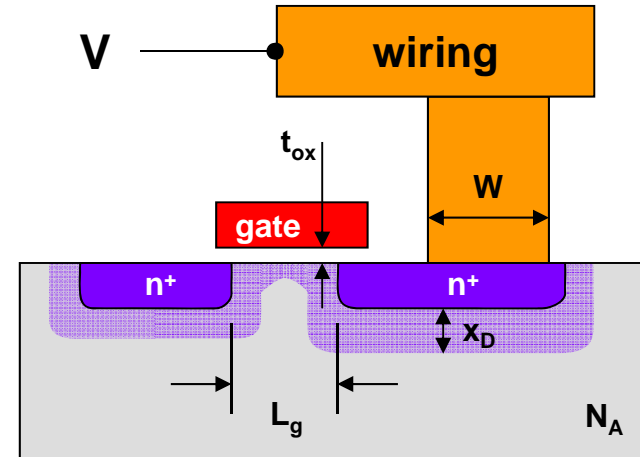
Beyond CMOS:

What is new about emerging technologies?

- **Miniaturization**
- **Parameterization**
- **Diversification**
- **Designability**

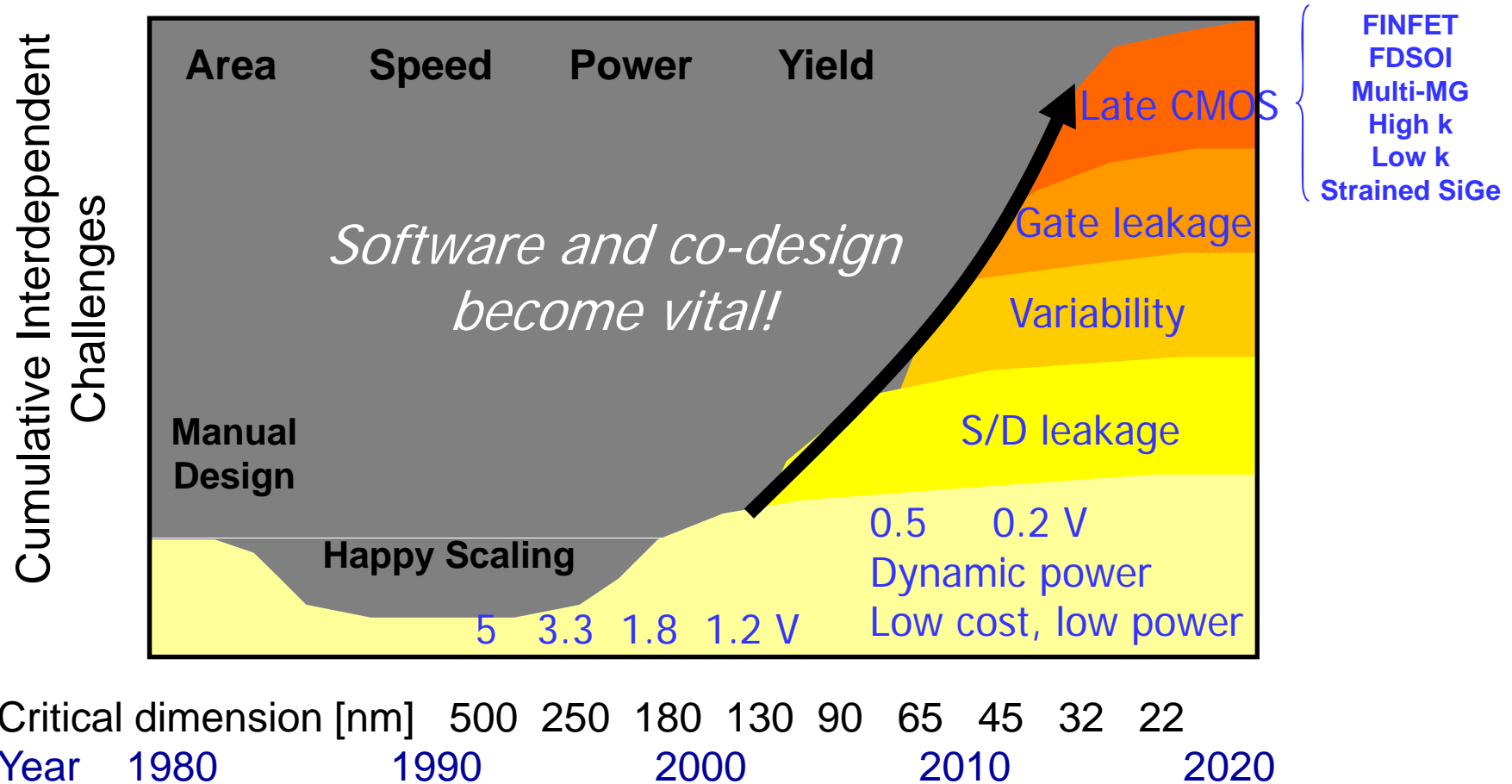
Constant Field Scaling

dimensions t_{ox} , L , W	$1/\alpha$
doping	α
voltage	$1/\alpha$
integration density	α^2
delay	$1/\alpha$
power dissipation/Tr	$1/\alpha^2$

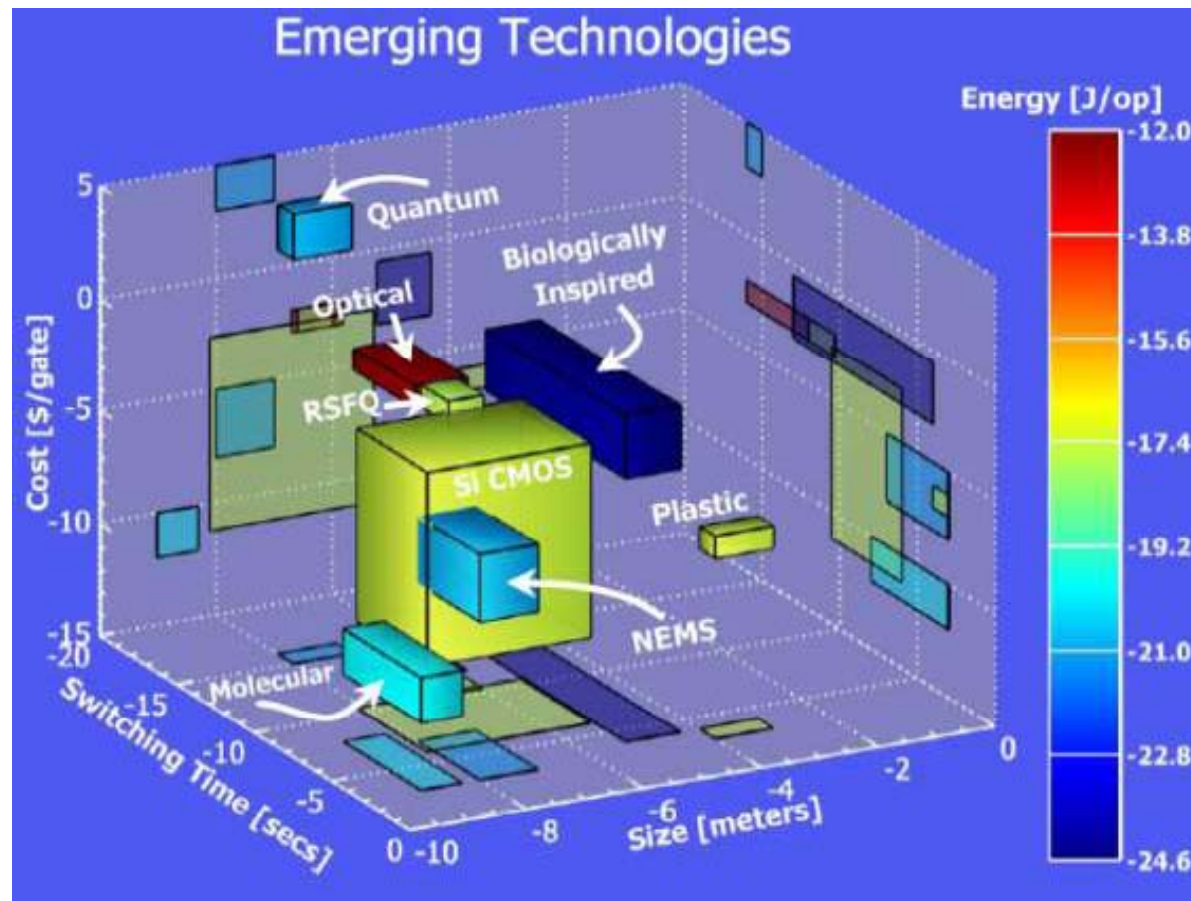


Source: More than Moore White Paper, ITRS (2011)

More Moore: Increasing complexity

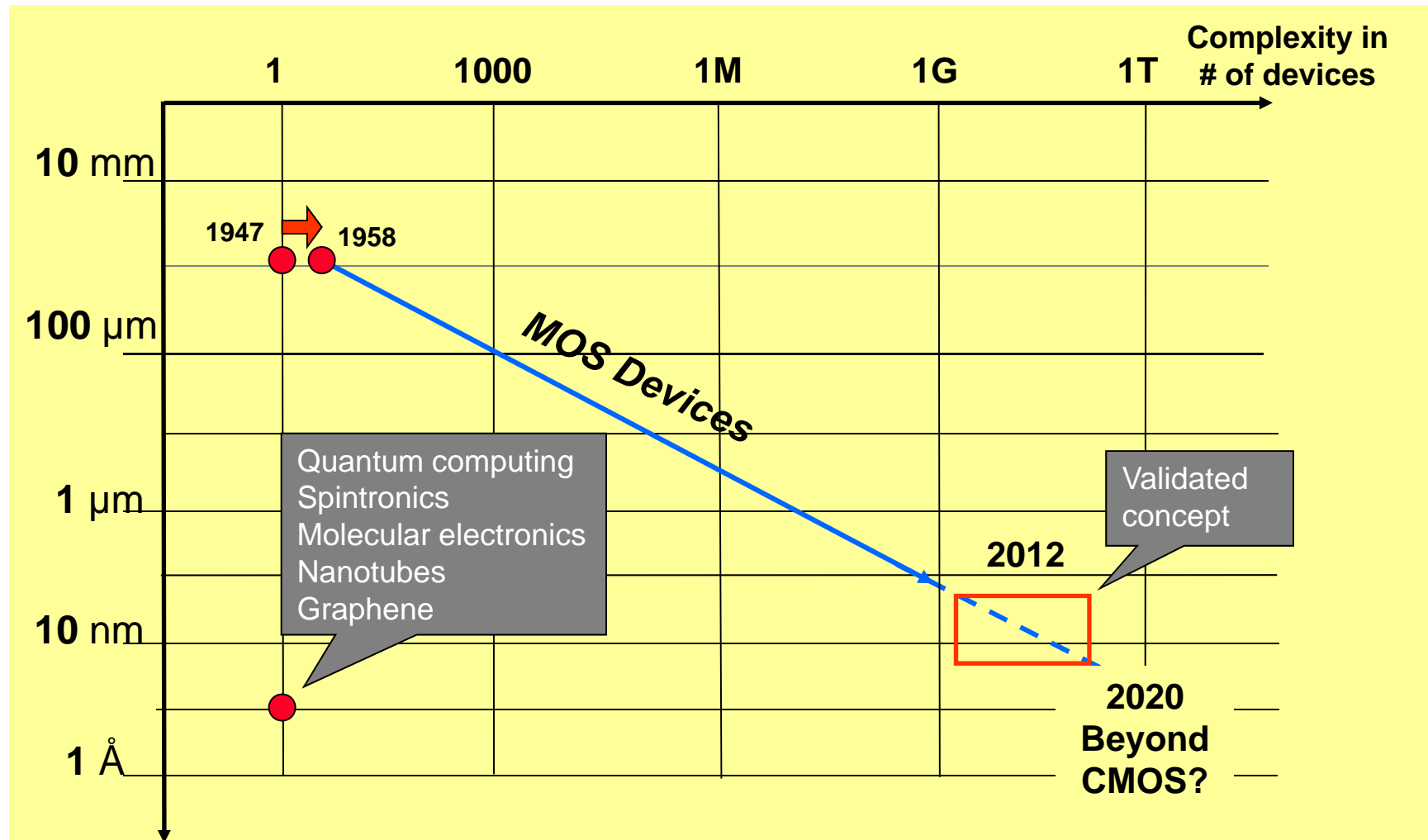


Parameterization of emerging technologies



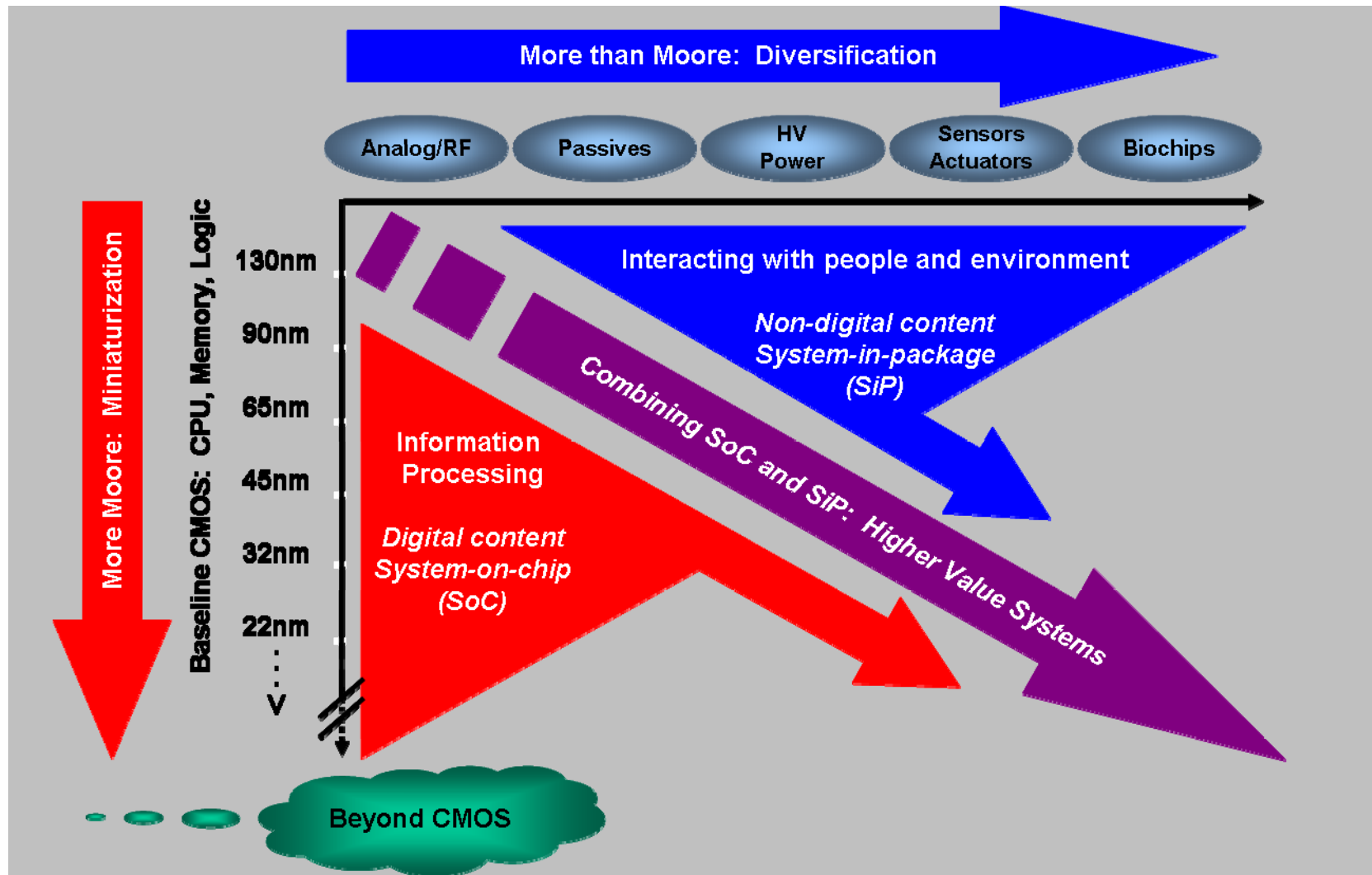
Source: ITRS

Reaching dimension/complexity limits



Source: STMicroelectronics

“More Moore” & “More than Moore”



Source: ITRS (2011)

“More Moore” & “More than Moore”

*Baseline
CMOS*

Memory

RF

*HV
Power*

Passives

*Sensors,
Actuators*

*Bio-chips,
Fluidics*

“More Moore”

“More than Moore”

Computing &
Data Storage

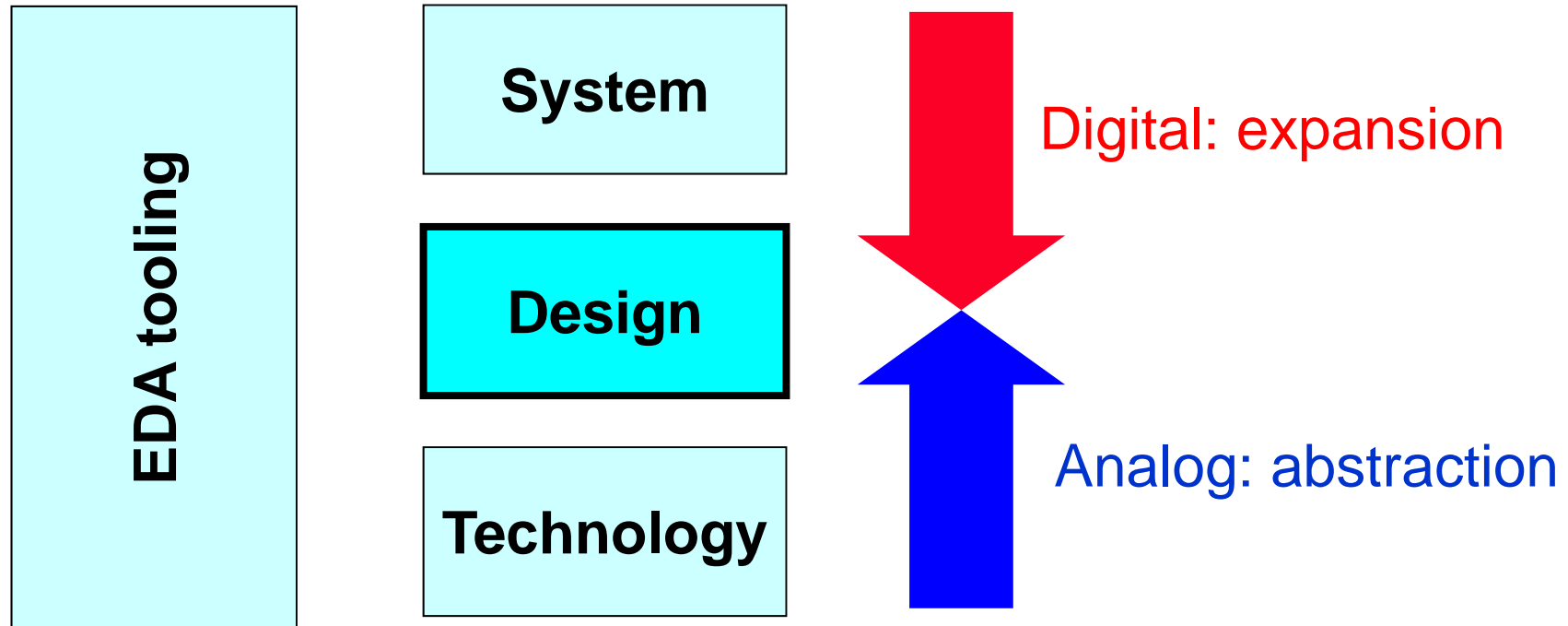
Sense, interact,
Empower

Heterogeneous Integration

System on Chip (SOC) and System In Package (SIP)

Source: ENIAC

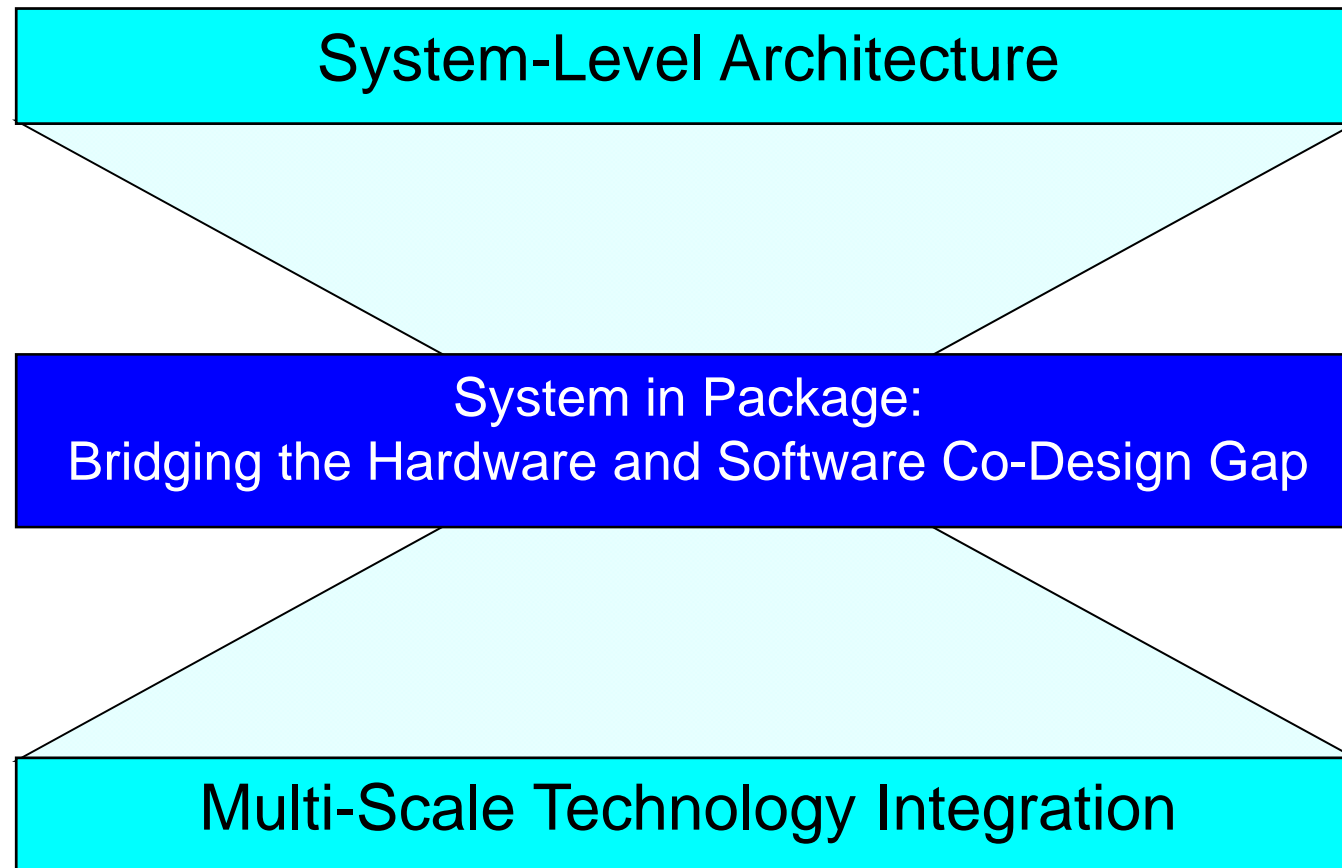
Design Hierarchy



- **Analog and digital approach design from opposite directions**
- **Mixed-signal: need to “meet in the middle”**

Source: Maarten Vertregt, NXP

MM & MtM: The Co-Design Challenge



MM & MtM: Design Aspects

- **More Moore:**
Design technologies that enable equivalent scaling (high performance, low power, high reliability, low cost, high design productivity)
 - Design for variability
 - Low power design (sleep modes, hibernation, clock gating, multi-VDD, ...)
 - Homogeneous and heterogeneous multicore SoC architectures
- **More than Moore:**
Design technologies that enable functional diversification
 - Heterogeneous system partitioning and simulation;
 - Analog and mixed signal design technologies for sensors and actuators;
 - New methods and tools for co-design and co-simulation of SiP, MEMS, and biotechnology